

# PATENT ASSIGNMENT

Electronic Version v1.1  
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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Jin Young Kim	11/11/2011
Doo Hyun Park	11/17/2011
Seung Jae Lee	11/11/2011
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Amkor Technology, Inc.
<b>Street Address:</b>	1900 South Price Road
<b>City:</b>	Chandler
<b>State/Country:</b>	ARIZONA
<b>Postal Code:</b>	85286-6604
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	13302501
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(831)655-0888
<b>Phone:</b>	(831)655-0880
<b>Email:</b>	rivkah@mckayhodgson.com
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Correspondent Name:</b>	McKay and Hodgson, LLP
<b>Address Line 1:</b>	1900 Garden Road, Suite 220
<b>Address Line 4:</b>	Monterey, CALIFORNIA 93940
<b>ATTORNEY DOCKET NUMBER:</b>	GK0051
<b>NAME OF SUBMITTER:</b>	Serge J. Hodgson
<b>Total Attachments: 2</b> source=GK0051_as_filed_assign#page1.tif source=GK0051_as_filed_assign#page2.tif	

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**PATENT**  
**REEL: 027267 FRAME: 0494**

ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, I,

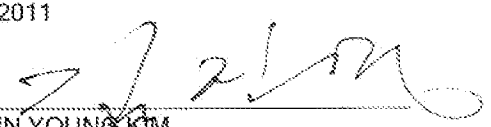
Jin Young Kim of #402-703 ho, Jugong Apt. 4 Danji, Chang 1-dong,  
Dobong-gu, Seoul, Rep. of Korea  
Doo Hyun Park of #402-703, Hyundai Morningside 4 Cha Apt., Sinhyeon-ri,  
Opo-eup, Gwangju-si, Kyunggi-do, Rep. of Korea  
Seung Jae Lee of #502-404, Humansia Apt, Gaun-dong, Namyangju-si,  
Kyunggi-do, Rep. of Korea

hereby sell, assign and transfer to Amkor Technology, Inc., a Delaware corporation, having a place of business at 1900 South Price Road, Chandler, AZ 85286-6604, its successors and assigns, the entire right, title and interest throughout the world in my invention in

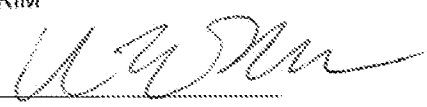
WAFER LEVEL FAN OUT PACKAGE AND METHOD OF FABRICATING  
WAFER LEVEL FAN OUT PACKAGE

for which I have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; I authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from me; I agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, its successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and I request the Commissioner of Patents and Trademarks to issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 11 day of Nov, 2011

  
JIN YOUNG KIM  
(Full Name)

Witnessed by:

  
Signature

Nov 11, 2011  
Date

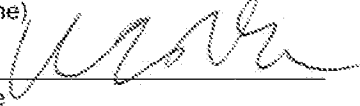
Do Hyun Na  
Printed Name

Assignment (continued)

Executed this 17 day of Nov, 2011

  
\_\_\_\_\_  
DOO HYUN PARK  
(Full Name)

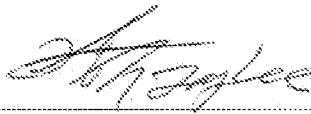
Witnessed by: \_\_\_\_\_

  
\_\_\_\_\_  
Signature

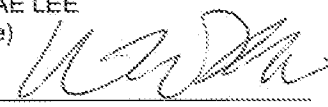
Nov. 17, 2011  
\_\_\_\_\_  
Date

Do Hyun Na  
\_\_\_\_\_  
Printed Name

Executed this 11 day of Nov, 2011

  
\_\_\_\_\_  
SEUNG JAE LEE  
(Full Name)

Witnessed by: \_\_\_\_\_

  
\_\_\_\_\_  
Signature

Nov 11, 2011  
\_\_\_\_\_  
Date

Do Hyun Na  
\_\_\_\_\_  
Printed Name